

# **ABSTRACT OF THE DISCLOSURE**

Disclosed is an imaging device package, in particular, comprising: a circuit board electrically connected to an image sensor chip through wire bonding; a housing adhered to the circuit board except for an area wire bonded with the sensor chip and having an opening at the top and steps with rounded sides around the opening; and a holder at the bottom having a ring-shaped opening corresponding to the steps around the opening of the housing for interference fitting around the steps and an lens internally fitted to the holder.